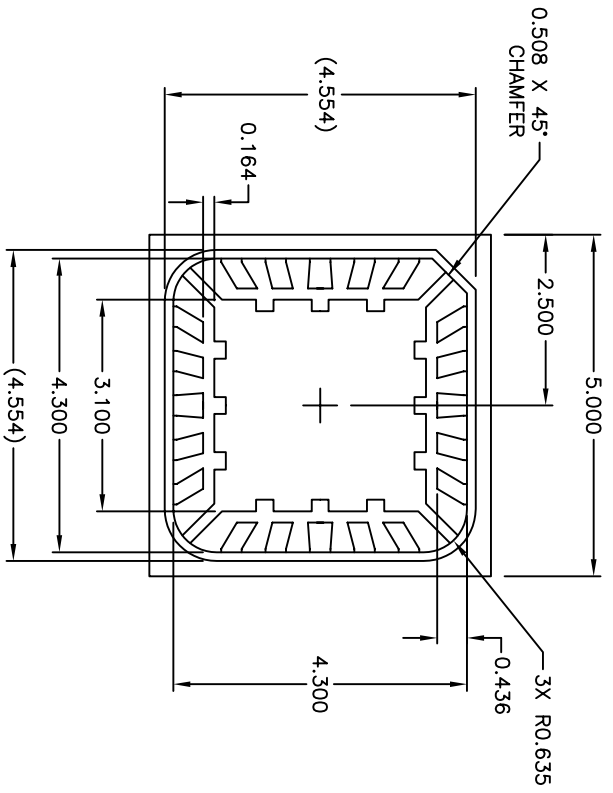


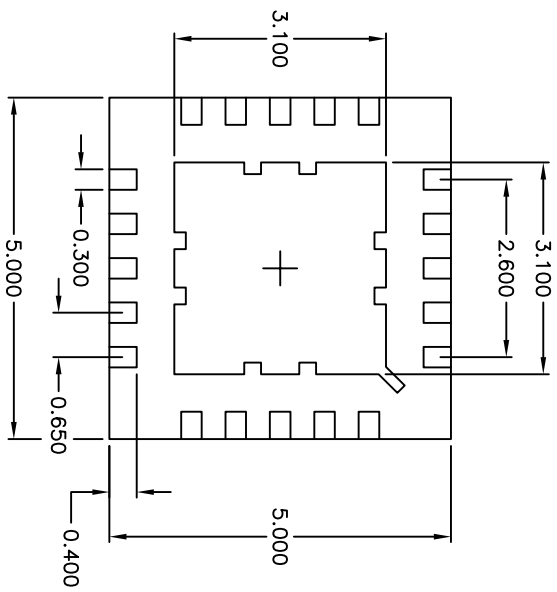
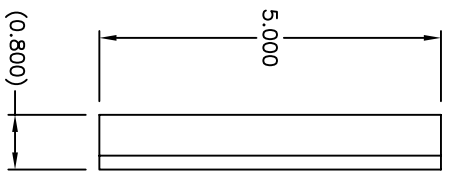
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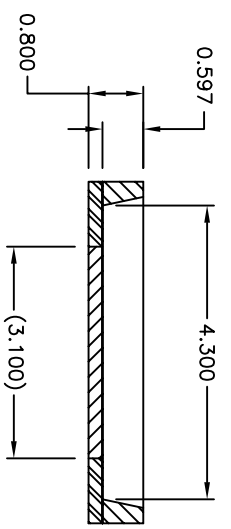
REVISIONS			APPROVED
ECN NO.	DATE	DESCRIPTION	
10491	10/27/05	PRODUCTION RELEASE	D.BENAVANDO



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, 194 FH.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. FRAME THICKNESS: 0.2030 ±.0076.
  5. DIE PAD: 3.100 X 3.100.
  6. JEDEC OUTLINE: MO-220 (VHHC-2).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± .1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	07/22/05
APP BY	P. FLASKERUD	DATE	07/22/05
CUSTOMER	----		

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**SEMPAC, INC.**  
 Open-Pak™ Technologies  
 www.sempac.com  
 568 E. WEDDELL DRIVE, SUITE 5  
 SUNNYSVALE, CALIFORNIA 94089  
 PHONE: (408) 400-9002 FAX: (408) 400-9006

SIZE	PART NO.	REV
A	MLP5X5-20-OP-01	1
SCALE	NONE	
FILE	MLP5X5-20-OP-01-R1.DWG	
SHEET	1 OF 1	

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